Patent claims

1.

A device for application of a liquid gluing system comprising at least two components, such as a resin component and a hardener component, the device comprising at least two hollow members (11, 11'), each member being provided with a row of orifices designed to apply the respective components onto a substrate (6) below the hollow members (11, 11'), and at least two trays (2, 2') one tray below each of the hollow members to receive surplus of the respective component not being applied onto the substrate, wherein the hollow members (11, 11') are adapted to be placed in the respective tray (2, 2') having the orifices below the level of the liquid in the tray.

2.

3.

The device according to claim 1, wherein the hollow members are removable connected to arms (15, 15') supporting the hollow members during application of the components.

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The device according to claim 1 or 2, wherein the hollow members are connected to the arms by means of brackets connected to the hollow members.

20 4.

The device according to one or more of the claims 1-3, wherein a lid (12, 12') for covering the opening of the tray (2, 2') is connected to the hollow member.

5.

The device according to any of the preceding claims, wherein the device comprises means for lowering the hollow member to placed in the respective tray during a stop in application.

6.

A method for avoiding plugging one or more orifices in a row of orifices in a hollow member for application of a component of a glue system to a substrate below the hollow member and where excess component is collected by means of a tray placed below the

hollow member, wherein the hollow member during a stop in the application, is placed in the respective tray so that the row of orifices at the hollow member is below the level of liquid in the tray.

5 7.

The method according to claim 6, wherein the hollow member is manually disconnected from a support member for supporting the hollow member during application and placed into the tray.

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